

CLAIMS

1. A prewetted cleaning wipe for cleaning surfaces and having low volatile organic chemical and low nonvolatile residue properties comprising a wipe substrate wetted with an aqueous solution of water and an effective amount of an acetylenic alcohol surface active agent.

2. The cleaning wipe of Claim 1 wherein the surface active agent is an acetylenic diol.

3. The cleaning wipe of Claim 1 wherein the surface active agent is present in the range of 0.001% to 0.5% by weight.

4. The cleaning wipe of Claim 1 wherein the surface active agent is present in the range of 0.01% to 0.3% by weight.

5. The cleaning wipe of Claim 1 wherein the ratio of surface active agent is present in the range of 0.05% to 0.2% by weight.

6. The cleaning wipe of Claim 1 wherein the low volatile organic chemical property of the surface active agent is a vapor pressure of at least 1×10^{-4} torr at 25°C.

7. The cleaning wipe of Claim 4 wherein the low nonvolatile residue property of surface active agent is a vapor pressure of at least 1×10^{-3} torr at 25°C.

8. The cleaning wipe of Claim 1 wherein the surface active agent is dimethyl octynediol.

9. The cleaning wipe of Claim 1 wherein the surface active agent is
5 tetramethyl decynediol.

10. The cleaning wipe of Claim 1 wherein the wipe substrate is selected from the group consisting of: cotton, abaca, polyester, nylon, polyester/cellulose, rayon, polypropylene, rayon/polyester, polypropylene/cellulose, polyurethane, cotton/polyester
10 and mixtures thereof.

11. The cleaning wipe of Claim 1 wherein the surface active agent is selected from the group consisting of: dimethyl octynediol; tetramethyl decynediol; 2,6,9,13-tetramethyl-2,12-tetradecadien-7-yne-6-9-diol; 2,6,9-trimethyl-2-decen-7-yne-6-9-diol;;
15 7,10-dimethyl-8-hexadecyne-7,10-diol; 2,4,7,9-tetramethyl-5-decyne-4,7-diol; 4,7-dimethyl-5-decyne-4,7-diol; 3,6-diethyl-4-octyne-3,6-diol; 2,5-dicyclopropyl-3-hexyne-2,5-diol; 2,5-diphenyl-3-hexyne-2,5-diol; 2,5,8,11-tetramethyl-6-dodecyne-5,8-diol.and mixtures thereof.

12. The cleaning wipe of Claim 1 wherein the ratio of surface active agent to
20 water is in the range of approximately 0.001% to 0.5% by weight.

13. The cleaning wipe of Claim 1 wherein the wipe substrate is a fibrous
substrate.

25

14. The cleaning wipe of Claim 1 wherein the wipe substrate is a woven fibrous substrate.

15. The cleaning wipe of Claim 1 wherein the wipe substrate is a nonwoven
5 fibrous substrate.

16. The cleaning wipe of Claim 1 wherein the wipe substrate is a sponge.

17. The cleaning wipe of Claim 1 wherein the water is high purity water.
10

18. The cleaning wipe of Claim 1 wherein the water is deionized water.

19. The cleaning wipe of Claim 1 wherein the water is distilled water.

15 20. A prewetted cleaning wipe for cleaning surfaces in an electronic materials fabricating area having a low volatile organic chemical content in the range of 0.001% to 0.5% by weight and low nonvolatile residue property of at least 1×10^{-4} torr at 25°C comprising; a woven fibrous polyester/cellulose wipe substrate wetted with an aqueous solution of high purity water selected from the group consisting of distilled water and
20 deionized water, and an effective amount of an acetylenic diol surface active agent selected from the group consisting of dimethyl octynediol, tetramethyl decynediol and mixtures thereof.

21. The cleaning wipe of Claim 20 wherein the surface active agent is in the
25 range of approximately 0.01% to 0.3% by weight.

22. The cleaning wipe of Claim 20 wherein the surface active agent is in the range of approximately 0.05% to 0.2% by weight.

5

N:\5918P\5918 P2 USA.doc